BGA Heat Sink - High Performance maxiFLOW/superGRIP



ATS Part#:

ATS-X50170P-C1-R0

Description:

17.00 x 17.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type: Heat Sink Attachment: Equivalent Part Number: N/A

maxiFLOW superGRIP

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 17x 17 mm components •
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs •
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a • PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB .

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	8.3 °C/W	6.9 °C/W	6 °C/W	5.4 °C/W	5 °C/W	4.6 °C/W	4.4 °C/W
	Ducted Flow	6.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	17.00 mm	17.00 mm	17.50 mm	31.9 mm	T766	BLUE-ANODIZED
•Image above is for illustration purpose only.	 Dimension Thermal papplication ATS resense performant ATS certifier 	performance data are n. rves the right to upda nce. ies that this heat sin	omponent size. height from the bottor e provided for referen ate or change its prov k assembly is RoHS istom options availat	nce only. Actual perfo ducts without notice -6 and REACH comp	ormance to improv	may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



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